


Full Material Declaration for attached parts list

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	<p>Diotech Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 01 January 2021 [Approved on 04 December 2025, 14:02 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	1.03%	Silicon	7440-21-3	100%
Die attach	Others (Rubber/non-thermoplastic Elastomer)	0.2%	4,4'-Sulfonylbisbenzamine	80-08-0	0.5%
			1,4-BIS(2,3-EPOXYPROPOXY)BUTANE	2425-79-8	1%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	16%
Encapsulation	EP (Epoxy resin)	55.86%	Silver	7440-22-4	82.5%
			Carbon black	1333-86-4	0.3%
			Silicon Dioxide	7631-86-9	3.8%
			Phenol, polymer with formaldehyde	9003-35-4	11%
			Fused Silica	60676-86-0	84.9%
Inner preparation	Gold	0.08%	Gold	7440-57-5	100%
Leadfinish	Tin plating	0.8%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	42.03%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-89 (H) Pb & H-free_02	Diode / Transistor SMD	0.0497	g

